

App. Ser. No. 10/683,622
Reply to Office action of February 24, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) An apparatus for testing ball grid arrays ("BGAs")[[,]] comprising:

a socket slot in a printed circuit board for receiving for holding a socket that is
used for testing supporting the BGAs solder balls, wherein the BGA solder balls are supported
by plural holding members of the socket ; and plural holding members that support the BGA sol-
5 der balls; and a via through the printed circuit board connects the BGA solder balls to a solder
ball at one end of the printed circuit board, wherein the solder ball at the end of the printed cir-
cuit board is connected to a testing module used for testing the BGAs.

2. (Currently Amended) The apparatus of Claim 1, wherein the socket top may have plural
prong-like holding members for supporting the solder balls are prong shaped.

3 – 4. (Cancelled)

5. (Currently Amended) The apparatus of Claim 1, wherein the holding members may be are
etched on a BGA socket top.

6. (Currently Amended) The apparatus of Claim 1, wherein the plural holding members are
flexible, rigid [[,]] and/or semi-rigid to provide support for the solder balls.